



Click [here](#) for the 3D model.

Dimensions

Chip Size	0603
L	1.6mm +/-0.1mm
W	0.8mm +/-0.1mm
T	0.8mm +/-0.1mm
B	0.4mm +/-0.2mm

Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	4000

General Information

Series	CBR-SMD RF Auto COG
Style	SMD Chip
Description	SMD, Fixed, RF, Ultra High Q, Low ESR, Class I
Features	Ultra High Q, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	false
Qualifications	AEC-Q200
AEC-Q200	Yes
Halogen Free	true
Typical Component Weight	5.29 mg
Notes	Solder Wave or Solder Reflow.
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	2.8 pF
Capacitance Tolerance	+/-0.1 pF
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MHz 1.0Vrms
Dissipation Factor	0.22% 1MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	10 GOhms
Quality Factor	456